1. Package summary

Dimensions (mm)	2.0 x 2.0 x 0.3
Terminal position code	Q (quad)
Package type descriptive code	SOT1261
Package outline version code	SOT1261-1
Manufacturer package code	SOT1261
Package type industry code	HX2QFN12
Package outline version description	plastic, thermal enhanced super thin quad flat package; no leads; 12 terminals; body 2.0 x 2.0 x 0.3 mm
Package style descriptive code	HXQFN (thermal enhanced extremely thin quad flatpack; no leads)
Package body material type	P
Mounting method type	S (surface mount)
Security status	COMPANY PUBLIC
Issue date	20-6-2014

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
A	seated height		0.28	-	0.3	0.33	mm
D	package length		1.95	-	2	2.05	mm
E	package width		1.95	-	2	2.05	mm
e	nominal pitch		-	-	0.5	-	mm
n_2	actual quantity of termination		-	-	12	-	

plastic, thermal enhanced super thin quad flat package; no leads; 12 terminals; body 2.0 x 2.0 x 0.3 mm

2. Package outline

HX2QFN12: plastic, thermal enhanced super thin quad flat package; no leads; 12 terminals; body 2.0 x 2.0 x 0.3 mm **SOT1261-1**

Dimensions: (mm are the orginal dimensons)

Unit		A	A$_1$	b	D$^{(1)}$	D$_h$	E$^{(1)}$	E$_h$	e	e$_1$	e$_2$	k	L	L$_1$	v	w	y	y$_1$
	max	0.33	0.05	0.25	2.05	1.10	2.05	1.10					0.35	0.10				
mm	nom	0.30	0.02	0.20	2.00	1.00	2.00	1.00	0.5	1.0	1.0	0.25	0.25	0.05	0.07	0.05	0.05	0.05
	min	0.28	0.00	0.15	1.95	0.85	1.95	0.85				0.20	0.15	0.00				

Note
1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot1261-1_po

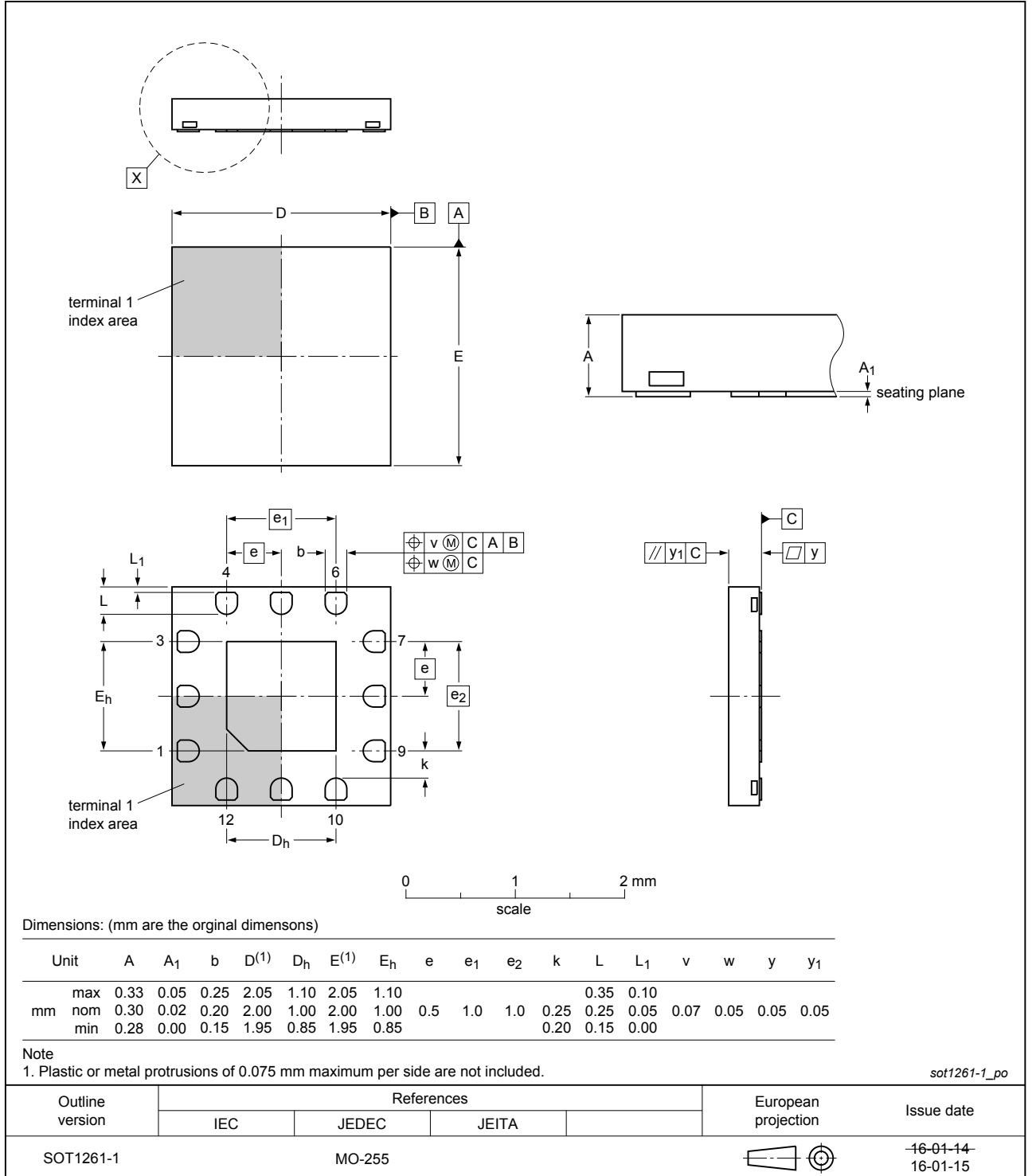| Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1261-1		MO-255				~~16-01-14~~ 16-01-15

Fig. 1.   Package outline HX2QFN12 (SOT1261-1)

plastic, thermal enhanced super thin quad flat package; no leads; 12 terminals; body 2.0 x 2.0 x 0.3 mm
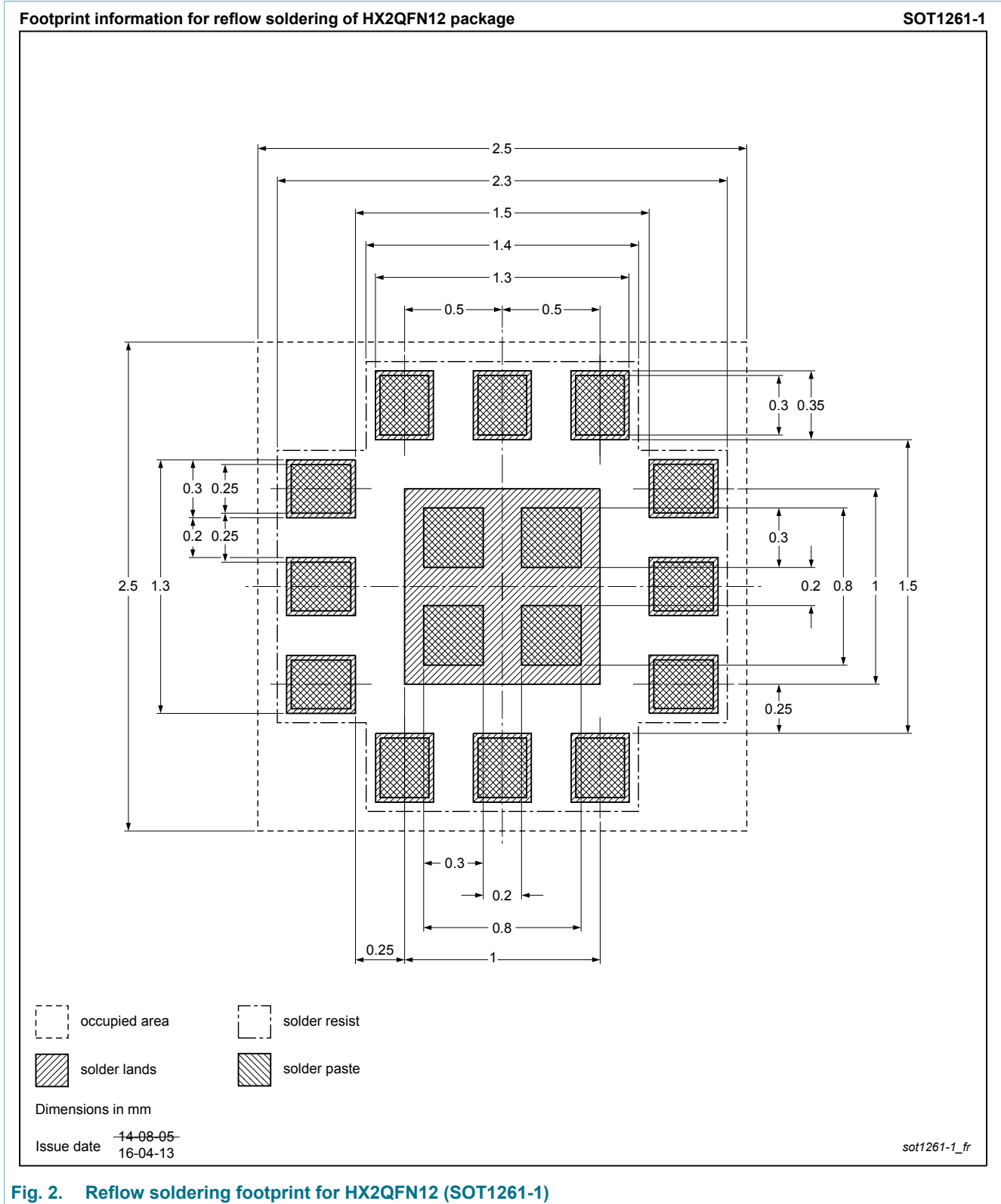
3. Soldering

Footprint information for reflow soldering of HX2QFN12 package
SOT1261-1

occupied area

solder resist

solder lands

solder paste

Dimensions in mm

Issue date 14-08-05
16-04-13

sot1261-1_fr

Fig. 2. **Reflow soldering footprint for HX2QFN12 (SOT1261-1)**

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5. Contents

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